



Material Content Data Sheet



Sales Product Name	AIDK16S65C5			Issued		4. May 2022		
MA#	MA005709286							
Package	PG-TO263-2-1			Weight*		1467.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	1.203	0.08	0.08	820	820
leadframe	inorganic material	phosphorus	7723-14-0	0.225	0.02		154	
	non noble metal	iron	7439-89-6	0.751	0.05		512	
	non noble metal	copper	7440-50-8	749.949	51.12	51.19	511143	511809
wire	non noble metal	aluminium	7429-90-5	1.630	0.11	0.11	1111	1111
encapsulation	inorganic material	zincoxide	1314-13-2	5.563	0.38		3792	
	miscellaneous	miscellaneous	-	22.252	1.52		15166	
	plastics	epoxy resin	-	83.445	5.69		56873	
	inorganic material	silicondioxide	60676-86-0	445.038	30.33	37.92	303325	379156
leadfinish	non noble metal	tin	7440-31-5	11.700	0.80	0.80	7974	7974
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5	
	non noble metal	nickel	7440-02-0	2.778	0.19	0.19	1893	1898
solder	non noble metal	tin	7440-31-5	0.020	0.00		13	
	noble metal	silver	7440-22-4	0.024	0.00		17	
	non noble metal	lead	7439-92-1	0.932	0.06	0.06	635	665
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.00		29	
	non noble metal	iron	7439-89-6	0.142	0.01		97	
	non noble metal	copper	7440-50-8	141.498	9.64	9.65	96441	96567
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with End-of-Life Vehicle (ELV) Directive 2000/53/EG and the ELV Annex II (2016/774/EU) and contains Pb according ELV Annex II (2016/774/EU) exemption 8(e), Lead in high melting temperature type solders.

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